

APPROVAL SHEET

MULTILAYER CERAMIC CAPACITORS

High Q / Low ESR Series (HH)

0201 to 0805 Sizes

NP0 Dielectric

Halogen Free & RoHS Compliance

*Contents in this sheet are subject to change without prior notice.



Approval Sheet

1. INTRODUCTION

MLCC consists of a conducting material and electrodes. To manufacture a chip-type SMT and achieve miniaturization, high density and high efficiency, ceramic condensers are used.

WTC HH series MLCC is used at high frequencies generally have a small temperature coefficient of capacitance, typical within the ±30ppm/C required for NP0 (C0G) classification and have excellent conductivity internal electrode. Thus, WTC HH series MLCC will be with the feature of low ESR and high Q characteristics.

2. FEATURES

- a. High Q and low ESR performance at high frequency.
- b. Quality improvement of telephone calls for low power loss and better performance.

3. APPLICATIONS

- Mobile telecommunication: Mobile phone, WLAN.
- RF module: Power amplifier, VCO.
- Tuners.

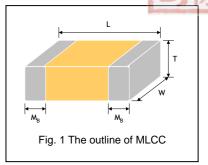
4. HOW TO ORDER

<u>HH</u>	<u>15</u>	<u>N</u>	<u>100</u>	<u>G</u>	<u>500</u>	<u>C</u>	I
<u>Series</u>	<u>Size</u>	Dielectric	Capacitance	<u>Tolerance</u>	Rated voltage	<u>Termination</u>	<u>Packaging</u>
HH=High Q/ Low ESR	03=0201 (0603) 15=0402 (1005) 18=0603 (1608) 21=0805 (2012)	N=NP0 (COG)	Two significant digits followed by no. of zeros. And R is in place of decimal point. PASSIVE SY eg.: R47=0.47pF 0R5=0.5pF 1R0=1.0pF 100=10x10° =10pF	A=±0.05pF B=±0.1pF C=±0.25pF D=±0.5pF F=±1% G=±2% J=±5%	Two significant digits followed by no. of zeros. And R is in place of decimal point. 100=10 VDC 160=16 VDC 250=25 VDC 500=50 VDC 101=100 VDC 201=200 VDC 251=250 VDC 501=500 VDC	C=Cu/Ni/Sn	T=7" reeled G=13" reeled
	15 =0402 (1005) 18 =0603 (1608)	(C0G)	digits followed by no. of zeros. And R is in place of decimal point. PASSIVE SY: eg.: R47=0.47pF 0R5=0.5pF 1R0=1.0pF 100=10x10°	B=±0.1pF C=±0.25pF D=±0.5pF F=±1% G=±2%	digits followed by no. of zeros. And R is in place of decimal point. 100=10 VDC 160=16 VDC 250=25 VDC 500=50 VDC 101=100 VDC 201=200 VDC 251=250 VDC	C =Cu/Ni/Sn	

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5. EXTERNAL DIMENSIONS

Size Inch (mm)	L (mm)	W (mm)	T (mm)/Symbol		Remark	M _B (mm)
0201 (0603)	0.6±0.03	0.3±0.03	0.3±0.03	L	#	0.15±0.05
0402 (1005)	1.00±0.05	0.50±0.05	0.50±0.05	N	#	0.25 +0.05/-0.10
	1.60±0.10	0.80±0.10	0.80±0.07	s		
0603 (1608)	1.60 +0.15/-0.10	0.80 +0.15/-0.10	0.80 +0.15/-0.10	х		0.40±0.15
			0.60±0.10	А		
0805 (2012)	2.00±0.15 1.25±0.10	1.25±0.10	0.80±0.10	В		0.50±0.20
			1.25±0.10	D	#	



6. GENERAL ELECTRICAL DATA

Dielectric	NPO /		
Size	0201, 0402, 0603, 0805		
Capacitance*	0.1pF to 3300pF		
	Cap≤5pF [#] [!] : A (±0.05pF), B (±0.1pF), C (±0.25pF)		
Capacitance tolerance	5pF <cap<10pf: (±0.25pf),="" (±0.5pf)<="" c="" d="" td=""></cap<10pf:>		
	Cap≥10pF: F (±1%), G (±2%), J (±5%) ANCE		
Rated voltage (WVDC)	10V, 16V, 25V, 50V, 100V, 200V, 250V, 500V, 630V		
*	Cap<30pF: Q≥400+20C		
Q*	Cap≥30pF: Q≥1000		
Insulation resistance at Ur	≥10GΩ or RxC≥100Ω-F whichever is smaller.		
Operating temperature	-55 to +125°C//		
Capacitance change	±30ppm		
Termination	Ni/Sn (lead-free termination)		

^{#1:} NP0, 0.1pF product only provide B tolerance

7. PACKAGING DIMENSION AND QUANTITY

Size	Thickness (mm)/Symbol		Pape	r tape	Plastic tape	
Size			7" reel	13" reel	7" reel	13" reel
0201	0.30±0.03	L	15,000	70,000	-	-
0402	0.50±0.05	N	10,000	50,000	-	-
	0.80±0.07	S	4.000	45.000	-	
0603	0.80 +0.15/-0.10	Х	4,000	15,000		-
	0.60±0.10	А	4.000	45.000		
0805	0.80±0.10	В	4,000	15,000	-	-
	1.25±0.10	D	-	-	3,000	10,000

Unit: pieces

[#] Reflow soldering only is recommended.

^{*} Measured at the conditions of 25℃ ambient temper ature and 30~70% related humidity.

Apply 1.0±0.2Vrms, 1.0MHz±10% for Cap≤1000pF and 1.0±0.2Vrms, 1.0kHz±10% for Cap>1000pF.

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8. CAPACITANCE RANGE

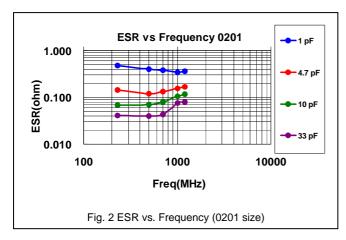
SIZE	
Rated Voltage 10 16 28 50 16 25 50 100 10 200 50 100 200 250 500 0 0 0 0 0 0 0 0	
0.1pF (0R2) 0.2pF (0R3) 0.4pF (0R4) 0.3pF (0R3) 0.4pF (0R4) 0.5pF (0R5) 0.4pF (0R6) 0.5pF	10
0.2pF (0R2)	
0.3pf (0R3) L L L N N N N N N N	
0.4pF (0R5)	
0.5pf (0R5)	
0.5pF (0R7)	
0.7pF (0R7)	
0.8pF (0R8) L L L L N N N N S S S S S B B B B B	
1.0pF (1R0)	
1.0pF (1R0)	
1.2pF (1R2)	
1.5pF (1R8)	
1.8pF (1R8)	
2.2pF (2R2) L L L L N N N N N S S S S S B B B B B B B B B B	
2.7pF (2R7) L L L L N N N N N S S S S S B B B B B B B B B B	
3.3pF (3R3) L L L L N N N N S S S S S S	
3.9pF (3R9) L L L L N N N N S S S S S B B B B B	
### 4.7pf (4R7)	
S.6pF (5R6)	
8.2pF (8R2)	
10pF (100) L L L N N N N N S S S S S	
12pF (120)	
15pF (150)	
18pF (180)	
39pF (390)	
Marcon Name	
S6pF (560)	
68pF (680) N N N N N S S S B	
82pF (820)	
100pF (101)	
120pF (121)	
150pF (151)	
180pF (181)	
N N N N N S S S S S D D D D D D D D D D	
270pF (271)	
N N N N S S S S D D D D	
N N N N S S S S D D D D N N N N S S S S S S S S S S S S S S S	
### ##################################	
560pF (561) SSSSSS 680pF (681) SSSSS 820pF (821) SSSSSS 1,000pF (102) SSSSSS 1,200pF (122) XXXXX 1,500pF (152) XXXXX 1,800pF (182) XXXXX 2,200pF (222) XXXXX	
680pF (681) SSSSS 820pF (821) SSSSS 1,000pF (102) SSSSS 1,200pF (122) XXXXX 1,500pF (152) XXXXX 1,800pF (182) XXXXX 2,200pF (222) XXXXX	
820pF (821) 1,000pF (102) 1,200pF (122) 1,500pF (152) 1,800pF (182) 2,200pF (222) S S S S S X X X X X X X	
1,000pF (102) 1,200pF (122) 1,500pF (152) 1,800pF (182) 2,200pF (222) S S S S X X X X X X X X X X X	
1,200pF (122)	
1,500pF (152)	
1,800pF (182)	
2,200pF (222) X X X	
3,300pF (332) X X X	

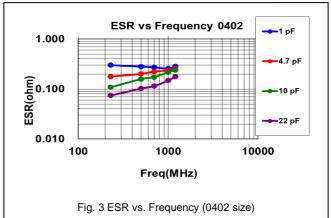
^{1.} The letter in cell is expressed the symbol of product thickness.

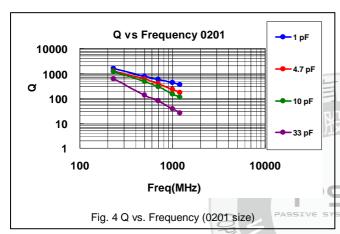
^{2.} For more information about products with special capacitance or other data, please contact WTC local representative.

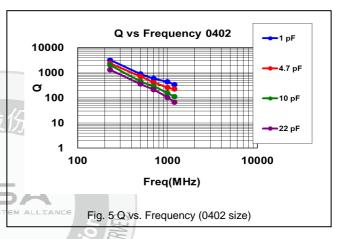
Approval Sheet

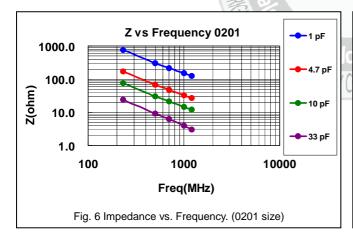
9. ELECTRICAL CHARACTERISTICS

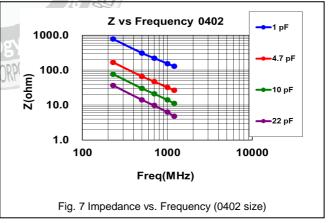


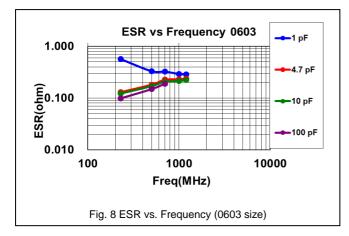


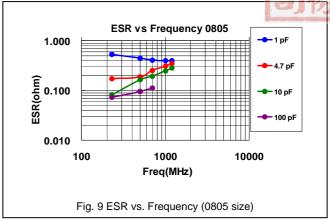


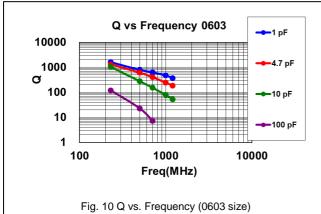


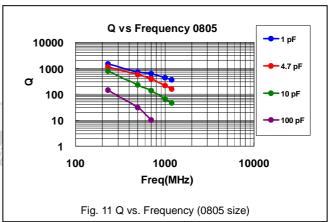


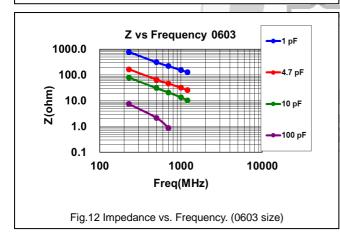


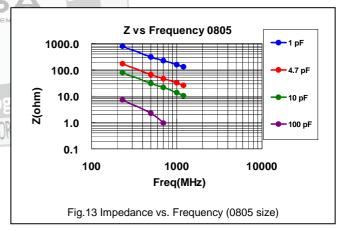


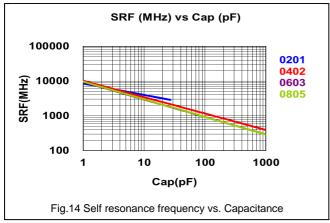
















10. RELIABILITY TEST CONDITIONS AND REQUIREMENTS

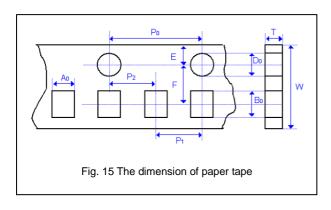
No.	Item	Test Conditions	Requirements
1.	Visual and		* No remarkable defect.
	Mechanical		* Dimensions to conform to individual specification sheet.
2.	Capacitance	Cap≤1000pF, 1.0±0.2Vrms, 1MHz±10%	* Shall not exceed the limits given in the detailed spec.
3.	Q/ D.F.	Cap>1000pF, 1.0±0.2Vrms, 1KHz±10%	* NP0: Cap≥30pF, Q≥1000; Cap<30pF, Q≥400+20C
	(Dissipation	At 25℃ ambient temperature.	
	Factor)		
4.	Dielectric	* To apply voltage: (≤100V) 250% of rated voltage.	* No evidence of damage or flash over during test.
	Strength	* Duration: 1 to 5 sec.	
		* Charge and discharge current less than 50mA.	
		* To apply voltage:	
		200V~300V ≥2 times VDC	
		500V~999V ≥1.5 times VDC	
		* Cut-off, set at 10mA	
		* TEST= 15 sec.	
		* RAMP=0	
5.	Insulation	Rated voltage:<200V	≥10GΩ
	Resistance	To apply rated voltage for max. 120 sec.	
		Rated voltage:200~630V	≥10GΩ or RxC≥100Ω-F whichever is smaller
		To apply rated voltage (500V max.) for 60 sec.	
6.	Temperature	With no electrical load.	* Capacitance change: within ±30ppm/°C
	Coefficient	Operating temperature: -55~125°C at 25°C	1/2 4/2
7.	Adhesive	* Pressurizing force :	* No remarkable damage or removal of the terminations.
	Strength of	2N (0201) and 5N (≤0603) and 10N (>0603)	
	Termination	* Test time: 10±1 sec.	
8.	Vibration	* Vibration frequency: 10~55 Hz/min.	* No remarkable damage.
	Resistance	* Total amplitude: 1.5mm	* Cap change and Q/D.F.: To meet initial spec.
		* Test time: 6 hrs. (Two hrs each in three mutually	
		perpendicular directions.)	E &
		* Cap./DF(Q) Measurement to be made after de-aging at	,0°.
_		150℃ for 1hr then set for 24±2 hrs at room temp.	011 6/2
9.	Solderability	1/60/4/0	95% min. coverage of all metalized area.
40		* Dipping time: 2±0.5 sec.	
10.	Bending Test		* No remarkable damage.
		of the pressurizing rod at a rate of about 1 mm per second until	
		the deflection becomes 1 mm and then the pressure shall be	(This capacitance change means the change of capacitance under
		maintained for 5±1 sec.	specified flexure of substrate from the capacitance measured before
		' *	the test.)
11	Decister 4	24±2 hrs.	* No remoduable demons
11.	Resistance to	* Solder temperature: 260±5°C	* No remarkable damage.
	Soldering Heat	•	* Cap change: within ±2.5% or ±0.25pF whichever is larger.
		* Preheating: 120 to 150°C for 1 minute before imme rse the	* Q/D.F., I.R. and dielectric strength: To meet initial requirements.
		capacitor in a eutectic solder. * Cap. / DE(O) / LB. Maasurament to be made after de aging.	* 25% max. leaching on each edge.
		* Cap. / DF(Q) / I.R. Measurement to be made after de-aging	
		at 150℃ for 1hr then set for 24±2 hrs at room temp.	

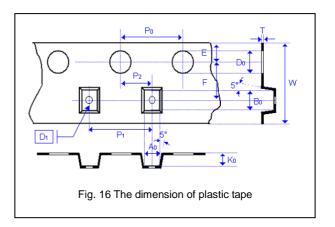


							manufi ()	
No.	Item		Test Condition	n		Requirements	9	
12.	Temperature	* Conduct th	he five cycles according to th	e temperatures a	nd	* No remarkable damage.		
	Cycle	time.				* Cap change: within ±2.5% or ±0.25pF whichever is larger.		
		Step	Temp. (℃)	Time (min.)		* Q/D.F., I.R. and dielectric strength: To meet initial require	ments.	
		:	fin. operating temp. +0/-3	30±3				
		§ 1	Room temp.	2~3				
		:	Max. operating temp. +3/-0	30±3				
		:	Room temp.	2~3				
			(Q) / I.R. Measurement to be r 1hr then set for 24±2 hrs at	•	ging			
13	Humidity	* Test temp.		room temp.		* No remarkable damage.		
.0.	(Damp Heat)		90~95% RH			* Cap change: within ±5.0% or ±0.5pF whichever is larger.		
	Steady State	1	500+24/-0hrs.			* Q/D.F. value:		
	Steady State	* Cap. / DF(Q) / I.R. Measurement to be made after de-aging				NP0: Cap≥30pF, Q≥350; 10pF≤Cap<30pF, Q≥275+2.5C		
			r 1hr then set for 24±2 hrs at		yiig	Cap<10pF; Q≥200+10C		
		at 150 0 101	1 1111 tileti set 101 2412 1113 at	room temp.		* I.R.: ≥1GΩor RxC≥50Ω-F whichever is smaller.		
14.	Humidity	* Test temp	.: 40±2℃			* No remarkable damage.		
	(Damp Heat)		90~95%RH			* Cap change: within ±7.5% or ±0.75pF whichever is larger.		
	Load	1	500+24/-0 hrs.			* Q/D.F. value:		
		* To apply v	voltage: rated voltage (Max.	500V)		NP0: Cap≥30pF, Q≥200; Cap<30pF, Q≥100+10/3C		
		* Cap. / DF	(Q) / I.R. Measurement to be	made after de-a	ging	* I.R.: ≥500MΩ or RxC≥25Ω-F whichever is smaller.		
		at 150℃ fc	or 1hr then set for 24±2 hrs a	t room temp.	1	7		
15.	High	* Test temp.	: 1			* No remarkable damage.		
	Temperature	NP0: 125:	±3℃	(齿股/	分文	* Cap change: within ±3.0% or ±0.3pF whichever is larger.		
	Load	* To apply voltage:			* Q/D.F. value:			
	(Endurance)	(1) <500V: 2	200% of rated voltage.			NP0: Cap≥30pF, Q≥350		
		(2) 500V: 15	50% of rated voltage.			10pF≤Cap<30pF, Q≥275+2.5C		
		(3) ≥630V: 1	120% of rated voltage.			Cap<10pF, Q≥200+10C		
		* Test time:	1000+24/-0 hrs.			* I.R.: ≥1GΩ or RxC≥50Ω-F whichever is smaller.		
		* Cap. / DF	(Q) / I.R. Measurement to be	made after de-ag	ging	TANCE C		
		at 150℃ for	r 1hr then set for 24±2 hrs at	room temp.		.9 意		

APPENDIXES

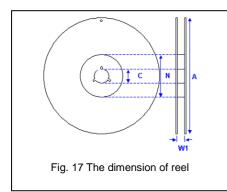
■ Tape & reel dimensions





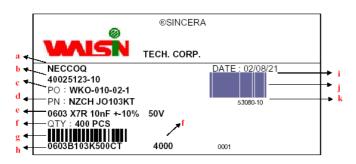
Size	0201	0402	0603		0805	
Thickness	L	N	S, X	Α	В	C, D, I
A ₀	0.40 +/-0.10	0.70 +/-0.20	1.05	1.50 +/-0.20	1.50 +/-0.20	< 1.80
B ₀	0.70 +/-0.10	1.20 +/-0.20	1.80 +/-0.30	2.30 +/-0.20	2.30 +/-0.20	< 2.70
Т	≦0.55	≦0,80	≦1.20	≦1.15	≦1.20	0.23 +/-0.1
K ₀	=	XV XX	7000	(E)	-	< 2.50
w	8.00 +/-0.30	8.00 +/-0.30	8.00 +/-0.30	8.00 +/-0.30	8.00 +/-0.30	8.00 +/-0.30
P ₀	4.00 +/-0.10	4.00 +/-0.10	4.00 +/-0.10	4.00 +/-0.10	4.00 +/-0.10	4.00 +/-0.10
10xP ₀	40.00 +/-0.10	40.00 +/-0.10	40.00 +/-0.20	40.00 +/-0.20	40.00 +/-0.20	40.00 +/-0.20
P ₁	2.00 +/-0.05	2.00 PASSIV +/-0.05	E SYST4.00 LLIANCE +/-0.10	4.00 +/-0.10	4.00 +/-0.10	4.00 +/-0.10
P ₂	2.00 +/-0.05	2.00 +/-0.05	2.00 +/-0.05	2.00 +/-0.05	2.00 +/-0.05	2.00 +/-0.05
D ₀	1.50 +0.1/-0	1.50 +0.1/-0	1.50 +0.1/-0	1.50 +0.1/-0	1.50 +0.1/-0	1.50 +0.1/-0
D ₁	-	Ch.	0		-	1.00 +/-0.10
E	1.75 +/-0.10	1.75 +/-0.10	1.75 +/-0.10	1.75 +/-0.10	1.75 +/-0.10	1.75 +/-0.10
F	3.50 +/-0.05	3.50	3.50	3.50 +/-0.05	3.50 +/-0.05	3.50 +/-0.05

MOTOPA COKLOVIUM



Size	0201, 0402, 0603, 0805					
Reel size	7"	10"	13"			
С	13.0+0.5/-0.2	13.0+0.5/-0.2	13.0+0.5/-0.2			
\mathbf{W}_1	8.4+1.5/-0	8.4+1.5/-0	8.4+1.5/-0			
Α	178.0±1.0	250.0±1.0	330.0±1.0			
N	60.0+1.0/-0	100.0±1.0	100±1.0			

■ Example of customer label



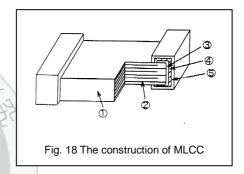
^{*}Customized label is available upon request



- a. Customer name
- b. WTC order series and item number
- c. Customer P/O
- d. Customer P/N
- e. Description of product
- f. Quantity
- g. Bar code including quantity & WTC P/N or customer
- h. WTC P/N
- i. Shipping date
- j. Order bar code including series and item numbers
- k. Serial number of label

Constructions

No.	Na	me	NP0
①	Ceramic	material	CaZrO₃ based
2	Inner el	ectrode	Ni (1)
3		Inner layer	Cu
4	Termination	Middle layer	Ni Ni
(5)		Outer layer	# Sn A 型



PASSIVE SYSTEM ALLIANCE

Storage and handling conditions

- (1) To store products at 5 to 40°C ambient temperature and 20 to 70%. related humidity conditions.
- (2) The product is recommended to be used within one year after shipment. Check solderability in case of shelf life extension is needed.

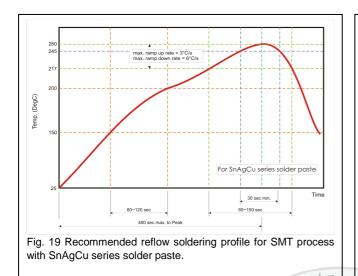
Cautions:

- a. The corrosive gas reacts on the terminal electrodes of capacitors, and results in the poor solderability. Do not store the capacitors in the ambience of corrosive gas (e.g., hydrogen sulfide, sulfur dioxide, chlorine, ammonia gas etc.)
- b. In corrosive atmosphere, solderability might be degraded, and silver migration might occur to cause low reliability.
- c. Due to the dewing by rapid humidity change, or the photochemical change of the terminal electrode by direct sunlight, the solderability and electrical performance may deteriorate. Do not store capacitors under direct sunlight or dewing condition. To store products on the shelf and avoid exposure to moisture.



■ Recommended soldering conditions

The lead-free termination MLCCs are not only to be used on SMT against lead-free solder paste, but also suitable against lead-containing solder paste. If the optimized solder joint is requested, increasing soldering time, temperature and concentration of N₂ within oven are recommended.



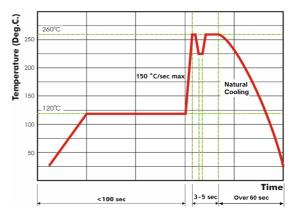


Fig. 20 Recommended wave soldering profile for SMT process with SnAgCu series solder.

